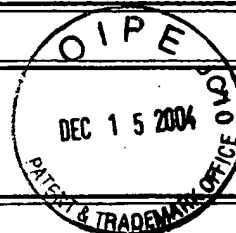


SUPPLEMENTAL APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

**Title of
Invention**

High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascene Interconnect Process

Application Type: regular, utility

Attorney Docket Number: 1875.0230001/JDE

Correspondence address:

Customer Number:

26111

26111

Continuing Data:

This is a Continuation of US application number 09/753,664, filed 2001-01-04.

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